

### Product / Package Information

Package	LFCSP - Stacked Die
Body Size (mm)	5 X 4 X 0.95 (1.47X2.15, 1.3 X 2.15 EP)
Lead Count	24
Terminal Finish	100 Sn
MS Number	MS001023C

### Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

### Materials Declaration

#### Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	2.13E-02	93.70	937000	38.87		388681
Thermosets	Epoxy Resin	Proprietary	6.80E-04	3.00	30000	1.24		12444
Thermosets	Phenol Resin	Proprietary	6.80E-04	3.00	30000	1.24		12444
Other inorganic materials	Carbon Black	1333-86-4	6.80E-05	0.30	3000	0.12		1244
Subtotal			2.27 E-02	100.00	1000000	41.48		414815

#### Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	2.22 E-02	96.20	962000	40.65		406482
Copper & its alloys	Nickel	7440-02-0	6.93 E-04	3.00	30000	1.27		12676
Copper & its alloys	Silicon	7440-21-3	1.50 E-04	0.65	6500	0.27		2746
Copper & its alloys	Magnesium	7439-95-4	3.47 E-05	0.15	1500	0.06		634
Subtotal			2.31 E-02	100.00	1000000	42.25		422538

#### Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	5.56 E-04	100.0	1000000	1.02		10173

#### External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.16 E-03	100.0	1000000	2.13		21287

#### Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	8.26 E-04	99.00	990000	1.51		15106
Precious metals	Palladium	7440-05-3	8.34 E-06	1.00	10000	0.02		153
Subtotal			8.34 E-04	100.0	1000000	1.53		15259

#### Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	4.60 E-03	100.0	1000000	8.42		84206

#### Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other organic materials	Resin	Proprietary	4.25 E-04	50.0	500000	0.78		7773
Other organic materials	Ethene, tetrafluoro- homopolymer	9002-84-0	3.83 E-04	45.0	450000	0.70		6996
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	4.25 E-05	5.0	50000	0.08		777
Subtotal			8.50 E-04	100.0	1000000	1.55		15546

#### Seal Glass

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Ceramics/Glass	Lead borosilicate glass	65997-17-3	7.74 E-04	87.5	875000	1.42		14154
Ceramics/Glass	Aluminosilicate glass	65997-17-3	1.11 E-04	12.5	125000	0.20		2022
			8.85 E-04	100.0	1000000	1.62		16176

<b>Package Totals</b>			<b>Weight (g)</b> 5.47 E-02			<b>Percentage (%)</b> 100		<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge.  
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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